

Curriculum Vitae of John A. Reed

EMPLOYMENT HISTORY:

The REED Company (April 1986—Present)

- Testified at depositions, Markman hearing, tutorial hearing, juried trials and before ITC Administrative Law Judges.
- Wrote & published tutorials on DRAM, SRAM, EPROM, EEPROM technology for client litigants for expert reports and courtroom demonstratives.
- Assisted lawyers & engineers with several semiconductor & computer firms in developing infringement and validity positions in licensing and litigation activities
- Wrote expert position papers for licensing, and expert reports/declarations for litigation
- Principal Expert Witness on Anti-Infringement for major Japanese respondent in ITC case between TI, complainant, and nine foreign co-respondents
- Circuit expert for major 2006 ITC hearing on behalf of complainant in patent infringement/validity case involving FLASH memory circuits and architecture
- Principal designer of SRAM cache elements for state-of-the-art RISC machines

VISIC, Inc. (November 1983—April 1986)

- Co-Founder/V.P. Engineering — Developed cost, yield, and production flow models for First-Round business plan; \$4.5 M was raised. Managed company's design and CAD technology development:
- Architected and Developed VISIC's first two DRAM's: The V64H1 & V16H4, two 35 NS "Hierarchical" RAM's
- Established & managed the implementation & usage of VISIC's CAD system
- Directed establishment & operation of State-of-the-Art memory test center
- Established product engineering capability
- Wrote application notes & technical briefs

RAMPOWER, Inc. (June 1974 — November 1983)

President, Senior Consultant — MOS/CMOS DRAM, SRAM, & non-volatile technology development. Some contributions to a sampling of clients:

BURROUGHS CORPORATION: (1974—77)

- Co-invented "Folded Bit Line" Memory Architecture
- Invented industry's 1st Dynamic Sense Amp
- Developed 4K DRAM device — First to apply folded bit line

NATIONAL SEMICONDUCTOR CORPORATION: (1974—82)

- Personally designed 4K DRAM device — "National's most successful development"
- Consulted on 16K-256K DRAM, various SRAM devices, as well as yield improvements
- Advised on management issues

EMPLOYMENT HISTORY: (Cont'd)

HUGHES AIRCRAFT: (1981—83)

- Single-handedly solved SOS SRAM problem related to fundamental transistor structure

LOCKHEED MISSILES & SPACE COMPANY: (1981—83)

- Invented & developed CMOS/MNOS means for replacing plated-wire memories.

NCR CORPORATION: (1981)

- Short (3-day) visit: 64K dynamic ROM was fraught with problems; Recommended list of changes which client implemented to convert yieldless ROM into production device

American Microsystems, Inc. (1972 —1974)

- Designed minicomputer DRAM memory systems
- Designed μ Processor-based intelligent terminal system
- Gave invited paper on “ μ Processors in Display Terminals”, IEEE workshop, 1973
- Product-engineered AMI DRAMs & ROMs

Intel Corporation (1970 —1972)

- Designed, characterized & brought i1103 to market — 1st Core-competitive DRAM
- Designed i2102, 1st 1K SRAM — helped spawn μ Processor revolution
- Developed i2105, High-speed mainframe Pseudo-SRAM

American Microsystems, Inc. (1968 —1970)

- Designed industry's first TTL compatible “large” ROM: 2560 Bits
- Managed joint development program between Shell Oil, SRI, AMI:
 - Resulted in original “Balanced Sense Amp” patent (Christensen)
 - Developed 1T Cell memory array test devices
 - Developed one of industry's first transient circuit simulators (MOSCAP)

PATENTS HELD: 14 Patents awarded, as inventor or co-inventor

EDUCATION: B.S.E.E. and M.S.E.E., University of California, Berkeley

HONOR SOCIETIES: Φ BK (Phi Beta Kappa), HKN (Eta Kappa Nu), TBPi (Tau Beta Pi)

PROFESSIONAL ORGANIZATIONS: Member, IEEE; Member and Diplomat,
American Board of Forensic Examiners